



1725

P/4076-59

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of
Yam Mo WONG et al.
Serial No.: 10/677,604
Filed: October 2, 2003

New York, New York
Date: February 13, 2004
Group Art Unit: 1725
Examiner: Not Yet Assigned

For: METHOD OF FORMING LOW WIRE LOOPS AND
WIRE LOOPS FORMED USING THE METHOD

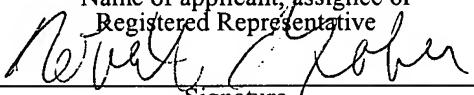
Commissioner for Patents
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SUBMISSION

Sir:

Submitted herewith is a copy of art together with a form listing the same for the convenience of the Examiner.

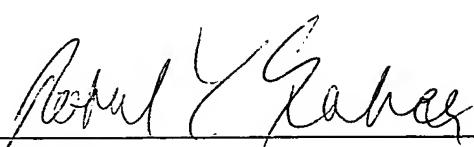
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Robert C. Faber
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February 13, 2004
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Respectfully submitted,



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Enclosures

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APPLICANT'S ART CITATION
(Use several sheets if necessary)

TRADEMARK CITATION

Application 10/677,604

OFGS File No. P/4076-59

Applicant Yam Mo WONG, et al.

Filing Date October 2, 2003

Group Art Unit 1725

U.S. PATENT DOCUMENTS (Copies not enclosed)

Examiner Initial	Document Number	Date MM-YYYY	Name	Class	Sub-class	Filing Date If Appropriate
	US- 5,156,323	10-1992	Kumazawa et al.	228	179	
	US- 5,961,029	10-1999	Nishiura et al.	228	180.5	
	US-					
	US-					
	US-					
	US-					
	US-					
	US-					
	US-					

FOREIGN PATENT DOCUMENTS

	Document Number	Date MM-YYYY	Country	Class	Sub-class	Translation	
						Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

Examiner

Date Considered

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.